Materials Declaration

Package	TQFP
Body Size	7 X 7 X 1.0
LeadCount	32
Option	Pb-free

Molding Compound

Item	% of Compound	Weight (g)	PPM
SiO2 Filler	82.5	7.13 E-02	523716
Epoxy Resin	8	6.91 E-03	50781
Phenol Resin	8	6.91 E-03	50781
Sb2O3	1.5	1.30 E-03	9519
Subtotal		8.64 E-02	634796

Leadframe

Item	% of Leadframe	Weight (g)	PPM
Cu	96.2	4.00 E-02	293969
Ni	3	1.25 E-03	9166
Si	0.65	2.70 E-04	1983
Mg	0.15	6.20 E-05	455
Subtotal		4.16 E-02	305573

Internal Leadframe Plating

	% of Plating	Weight (g)	PPM
Ag	100	4.12 E-04	3026

External Leadframe Plating

Item	% of Plating	Weight (g)	PPM
Sn	100	3.62 E-03	26610

Bond Wires

	% of Wire	Weight (g)	PPM
Au	99.99	5.46 E-04	4010

Chip

	% of Chip	Weight (g)	PPM
Si	100	2.81 E-03	20638

Die Attach

Item	% of Die Attach	Weight (g)	PPM
Ag	75.47	5.49 E-04	4032
Epoxy resin	18.87	1.37 E-04	1006
Gamma Butyrolactone	2.83	2.10 E-05	154
Curing agent & hardener	2.83	2.10 E-05	154
Subtotal		7.28 E-04	5347

Molding Compound

Item	PPM	Method
Pb	None Detected	EPA 3051/3052. ICP-OES
Cd	None Detected	EPA 3051/3052. ICP-OES
Hg	None Detected	EPA 3051/3052. ICP-OES
Cr+6	None Detected	USEPA 3060A & 7196A. UV-VIS.
PBB	None Detected	USEPA 3540C/3550C.Analysis was performed by GC/MS.
PBDE	None Detected	USEPA 3540C/3550C.Analysis was performed by GC/MS.

Die Attach Paste

Item	PPM	Method
Pb	None Detected	EPA 3051/3052. ICP-OES
Cd	None Detected	EPA 3051/3052. ICP-OES
Hg	None Detected	EPA 3051/3052. ICP-OES
Cr+6	None Detected	USEPA 3060A & 7196A. UV-VIS.
PBB	None Detected	USEPA 3540C/3550C.Analysis was performed by GC/MS.
PBDE	None Detected	USEPA 3540C/3550C.Analysis was performed by GC/MS.

Package Totals

Weight (g)	PPM
1.36 E-01	1000000

Note: The information provided in this declaration are true to the best of ADI's knowledge.
ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability to any inaccuracy of such information.

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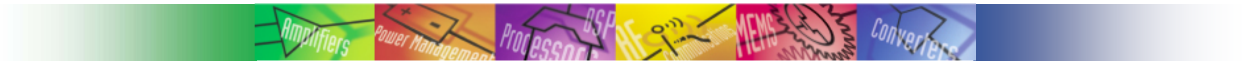

Materials Declaration

Package	TQFP
Body Size	7 X 7 X 1.0
LeadCount	32
Option	SnPb

Molding Compound

Item	% of Compound	Weight (g)	PPM
SiO2 Filler	82.5	7.13 E-02	523716
Epoxy Resin	8	6.91 E-03	50781
Phenol Resin	8	6.91 E-03	50781
Sb2O3	1.5	1.30 E-03	9519
		8.64 E-02	634796

Leadframe

Item	% of Leadframe	Weight (g)	PPM
Cu	96.2	4.00 E-02	293969
Ni	3	1.25 E-03	9166
Si	0.65	2.70 E-04	1983
Mg	0.15	6.20 E-05	455
		4.16 E-02	305573

Internal Leadframe Plating

	% of Plating	Weight (g)	PPM
Ag	100	4.12 E-04	3026

External Leadframe Plating

Item	% of Plating	Weight (g)	PPM
Sn	85	3.08 E-03	22621
Pb	15	5.43 E-04	3988
		3.62 E-03	26610

Bond Wires

	% of Wire	Weight (g)	PPM
Au	99.99	5.46 E-04	4010

Chip

	% of Chip	Weight (g)	PPM
Si	100	2.81 E-03	20638

Die Attach

Item	% of Die Attach	Weight (g)	PPM
Ag	75.47	5.49 E-04	4032
Epoxy resin	18.87	1.37 E-04	1006
Gamma Butyrolactone	2.83	2.10 E-05	154
Curing agent & hardener	2.83	2.10 E-05	154
		7.28 E-04	5347

Package Totals

Weight (g)	PPM
1.36 E-01	1000000

Molding Compound

Item	PPM	Method
Pb	None Detected	EPA 3051/3052. ICP-OES
Cd	None Detected	EPA 3051/3052. ICP-OES
Hg	None Detected	EPA 3051/3052. ICP-OES
Cr+6	None Detected	USEPA 3060A & 7196A. UV-VIS.
PBB	None Detected	USEPA 3540C/3550C.Analysis was performed by GC/MS.
PBDE	None Detected	USEPA 3540C/3550C.Analysis was performed by GC/MS.

Die Attach Paste

Item	PPM	Method
Pb	None Detected	EPA 3051/3052. ICP-OES
Cd	None Detected	EPA 3051/3052. ICP-OES
Hg	None Detected	EPA 3051/3052. ICP-OES
Cr+6	None Detected	USEPA 3060A & 7196A. UV-VIS.
PBB	None Detected	USEPA 3540C/3550C.Analysis was performed by GC/MS.
PBDE	None Detected	USEPA 3540C/3550C.Analysis was performed by GC/MS.

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